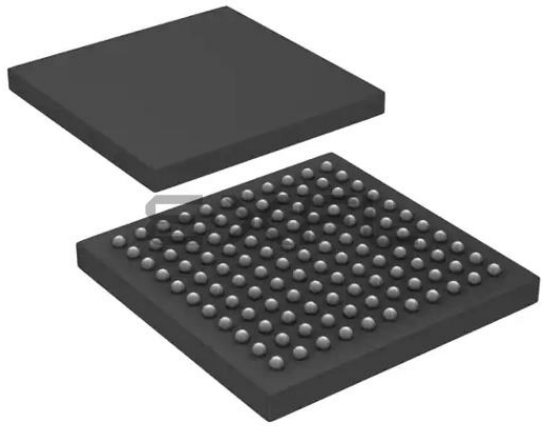
Microchip Technology - PIC24EP512GU810T-I/BG Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	83
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 32x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	121-TFBGA
Supplier Device Package	121-TFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512gu810t-i-bg

NOTES:

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 4. "Program Memory"** (DS70613) of the "*dsPIC33E/PIC24E Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

The device architecture features separate program and data memory spaces and buses. This architecture also allows the direct access of program memory from the data space during code execution.

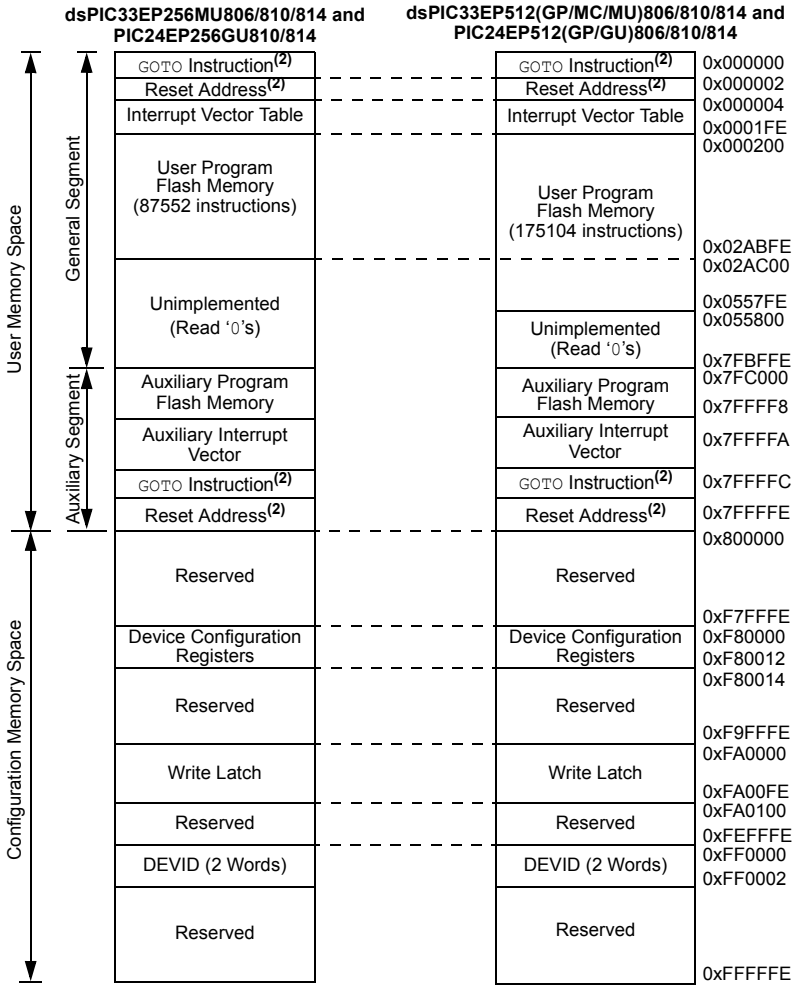
4.1 Program Address Space

The device program address memory space is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit PC during program execution, or from table operation or data space remapping as described in **Section 4.8 "Interfacing Program and Data Memory Spaces"**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of `TBLRD/TBLWT` operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

The device program memory map is shown in Figure 4-1.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 DEVICES(1)



Note 1: Memory areas are not shown to scale.

2: The Reset location is controlled by the Reset Target Vector Select bit, RSTPRI (FICD<2>). See **Section 29.0 "Special Features"** for more information.

4.8.1 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the Program Space without going through data space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a Program Space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit wide word address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

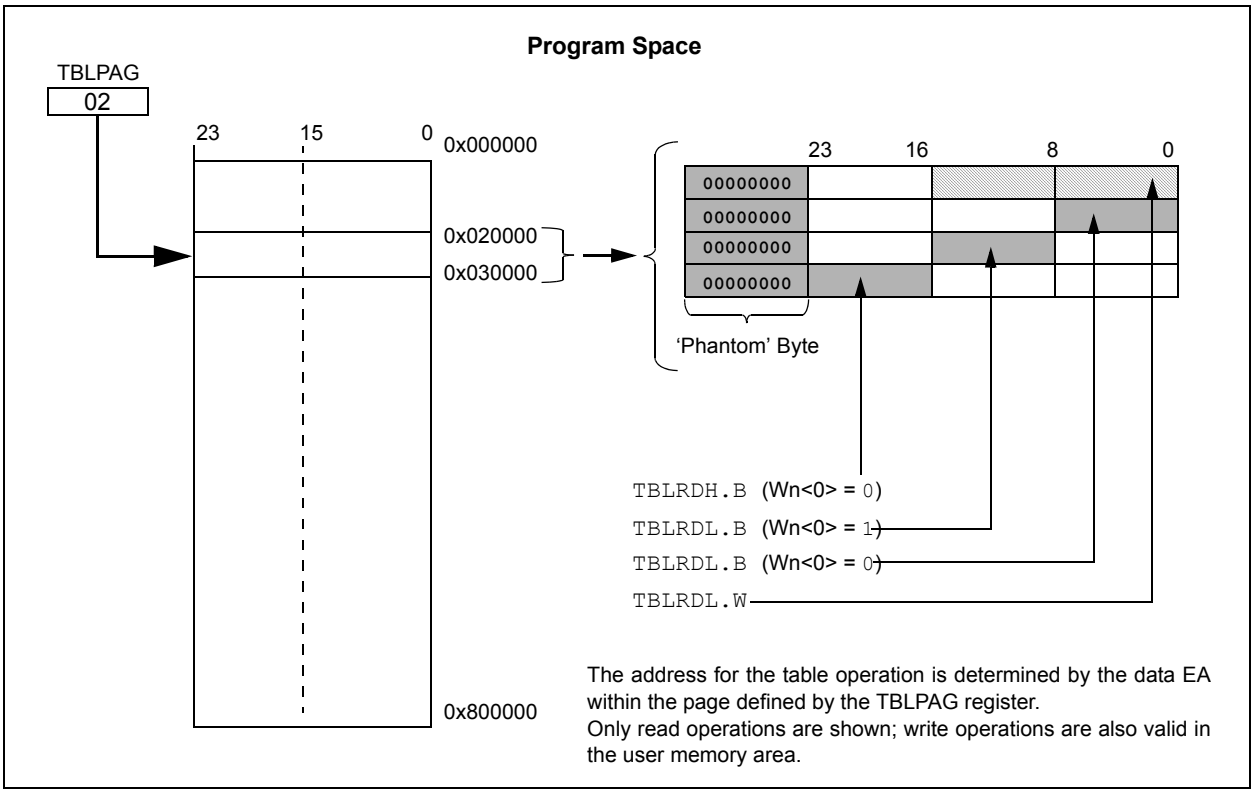
Two table instructions are provided to move byte or word-sized (16-bit) data to and from Program Space. Both function as either byte or word operations.

- TBLRDL (Table Read Low):
  - In Word mode, this instruction maps the lower word of the Program Space location (P<15:0>) to a data address (D<15:0>).
  - In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is '1'; the lower byte is selected when it is '0'.
- TBLRDH (Table Read High):
  - In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. The 'phantom' byte (D<15:8>), is always '0'.
  - In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address, in the TBLRDL instruction. The data is always '0' when the upper 'phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a Program Space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user application and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

FIGURE 4-13: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. "Flash Programming"** (DS70609) of the *"dsPIC33E/PIC24E Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows a dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear ($\overline{MCLR}$). This allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (table read) and TBLWT (table write) instructions. With RTSP, the user application can write program memory data either in blocks or 'rows' of 128 instructions (384 bytes) at a time or a single program memory word, and erase program memory in blocks or 'pages' of 1024 instructions (3072 bytes) at a time.

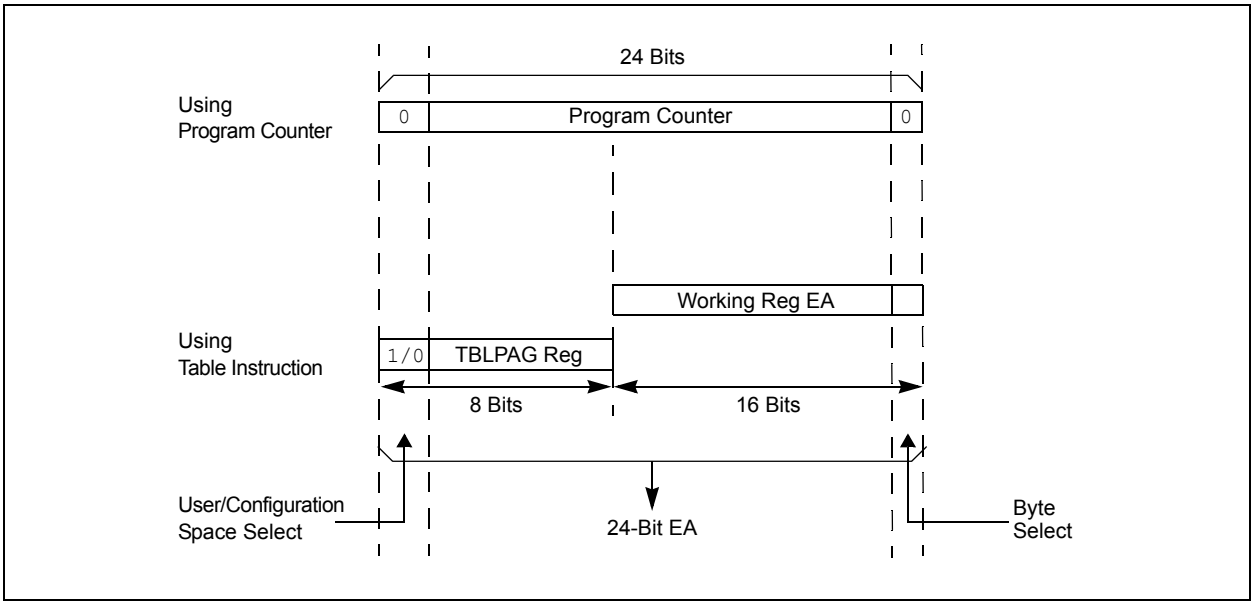
5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the table read and table write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits<7:0> of the TBLPAG register and the Effective Address (EA) from a W register, specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



NOTES:

11.4.4.2 Virtual Connections

The dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 devices support virtual (internal) connections to the output of the comparator modules, CMP1OUT, CMP2OUT and CMP3OUT (see Figure 25-1 in **Section 25.0 "Comparator Module"**). In addition, dsPIC33EPXXXMU806/810/814 devices support virtual connections to the filtered QEI module inputs, FINDX1, FHOME1, FINDX2 and FHOME2 (see Figure 17-1 in **Section 17.0 "Quadrature Encoder Interface (QEI) Module (dsPIC33EPXXX(MC/MU)8XX Devices Only)"**.

Virtual connections provide a simple way of inter-peripheral connection without utilizing a physical pin. For example, by setting the FLT1R<6:0> bits of the RPINR12 register to the value of 'b0000001, the output of the analog comparator, CMP1OUT, will be connected to the PWM Fault 1 input, which allows the analog comparator to trigger PWM Faults without the use of an actual physical pin on the device.

Virtual connection to the QEI module allows peripherals to be connected to the QEI digital filter input. To utilize this filter, the QEI module must be enabled, and its inputs must be connected to a physical RPn/RPIn pin. Example 11-2 illustrates how the input capture module can be connected to the QEI digital filter.

11.4.4.3 Mapping Limitations

The control schema of the peripheral select pins is not limited to a small range of fixed peripheral configurations. There are no mutual or hardware enforced lockouts between any of the peripheral mapping SFRs. Literally any combination of peripheral mappings across any or all of the RPn/RPIn pins is possible. This includes both many-to-one and one-to-many mappings of peripheral inputs and outputs to pins. While such mappings may be technically possible from a configuration point of view, they may not be supportable from an electrical point of view.

EXAMPLE 11-2: CONNECTING IC1 TO HOME1 DIGITAL FILTER INPUT ON PIN 3 OF THE dsPIC33EP512MU810 DEVICE

```
RPINR15 = 0x5600;      /* Connect the QEI1 HOME1 input to RP86 (pin 3) */
RPINR7 = 0x009;        /* Connect the IC1 input to the digital filter on the FHOME1 input */

QEI1IOC = 0x4000;      /* Enable the QEI digital filter */
QEI1CON = 0x8000;      /* Enable the QEI module */
```

REGISTER 11-18: RPINR17: PERIPHERAL PIN SELECT INPUT REGISTER 17 (dsPIC33EPXXXMU806/810/814 DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	HOME2R<6:0>(1)						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	INDX2R<6:0>(1)						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **HOME2R<6:0>:** Assign QEI2 HOME2 (HOME2) to the Corresponding RPn/RPIn Pin bits(1) (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP127
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **INDX2R<6:0>:** Assign QEI2 INDEX2 (INDX2) to the Corresponding RPn/RPIn Pin bits(1) (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP127
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

Note 1: These bits are available on dsPIC33EPXXX(MC/MU)806/810/814 devices only.

13.0 TIMER2/3, TIMER4/5, TIMER6/7 AND TIMER8/9

Note 1: This data sheet summarizes the features of the dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 11. "Timers"** (DS70362) of the *"dsPIC33E/PIC24E Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer2/3, Timer4/5, Timer6/7 and Timer8/9 modules are 32-bit timers, which can also be configured as four independent 16-bit timers with selectable operating modes.

As a 32-bit timer, Timer2/3, Timer4/5, Timer6/7 and Timer8/9 operate in three modes:

- Two Independent 16-Bit Timers (e.g., Timer2 and Timer3) with all 16-Bit Operating modes (except Asynchronous Counter mode)
- Single 32-Bit Timer
- Single 32-Bit Synchronous Counter

They also support these features:

- Timer Gate Operation
- Selectable Prescaler Settings
- Timer Operation during Idle and Sleep modes
- Interrupt on a 32-Bit Period Register Match
- Time Base for Input Capture and Output Compare Modules (Timer2 and Timer3 only)
- ADC1 Event Trigger (Timer2/3 only)
- ADC2 Event Trigger (Timer4/5 only)

Individually, all eight of the 16-bit timers can function as synchronous timers or counters. They also offer the features listed above, except for the event trigger; this is implemented only with Timer2/3. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON, T3CON, T4CON, T5CON, T6CON, T7CON, T8CON and T9CON registers. T2CON, T4CON, T6CON and T8CON are shown in generic form in Register 13-1. T3CON, T5CON, T7CON and T9CON are shown in Register 13-2.

For 32-bit timer/counter operation, Timer2, Timer4, Timer6 or Timer8 is the least significant word; Timer3, Timer5, Timer7 or Timer9 is the most significant word of the 32-bit timers.

Note: For 32-bit operation, T3CON, T5CON, T7CON and T9CON control bits are ignored. Only T2CON, T4CON, T6CON and T8CON control bits are used for setup and control. Timer2, Timer4, Timer6 and Timer8 clock and gate inputs are utilized for the 32-bit timer modules, but an interrupt is generated with the Timer3, Timer5, Ttimer7 and Timer9 interrupt flags.

A block diagram for an example 32-bit timer pair is shown Figure 13-3.

Note: Only Timer2, 3, 4 and 5 can trigger a DMA data transfer.

REGISTER 16-20: TRIGx: PWMx PRIMARY TRIGGER COMPARE VALUE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **TRGCMP<15:0>:** PWM Primary Trigger Control Value bits

When the primary PWM functions in local time base, this register contains the compare values that can trigger the ADC module.

REGISTER 16-22: LEBCONx: LEADING-EDGE BLANKING CONTROL REGISTER x

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH(1)	BCL(1)	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxH

bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxH

bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxL

bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxL

bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected Fault input
0 = Leading-Edge Blanking is not applied to selected Fault input

bit 10 **CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected current-limit input
0 = Leading-Edge Blanking is not applied to selected current-limit input

bit 9-6 **Unimplemented:** Read as '0'

bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
0 = No blanking when selected blanking signal is high

bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
0 = No blanking when selected blanking signal is low

bit 3 **BPHH:** Blanking in PWMxH High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high
0 = No blanking when PWMxH output is high

bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low
0 = No blanking when PWMxH output is low

bit 1 **BPLH:** Blanking in PWMxL High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high
0 = No blanking when PWMxL output is high

bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low
0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

REGISTER 23-2: AD1CON2: ADC1 CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
VCFG<2:0>			—	—	CSCNA	CHPS<1:0>	
bit 15							bit 8

R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUFS	SMPI<4:0>					BUFM	ALTS
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **VCFG<2:0>:** Converter Voltage Reference Configuration bits

	VREFH	VREFL
000	AVDD	Avss
001	External VREF+	Avss
010	AVDD	External VREF-
011	External VREF+	External VREF-
1xx	AVDD	Avss

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **CSCNA:** Input Scan Select bit
1 = Scans inputs for CH0+ during Sample A bit
0 = Does not scan inputs

bit 9-8 **CHPS<1:0>:** Channel Select bits
When AD12B = 1, CHPS<1:0> is: U-0, Unimplemented, Read as '0':
1x = Converts CH0, CH1, CH2 and CH3
01 = Converts CH0 and CH1
00 = Converts CH0

bit 7 **BUFS:** Buffer Fill Status bit (only valid when BUFM = 1)
1 = ADC is currently filling the second half of the buffer; the user application should access data in the first half of the buffer
0 = ADC is currently filling the first half of the buffer; the user application should access data in the second half of the buffer

bit 6-2 **SMPI<4:0>:** Increment Rate bits
When ADDMAEN = 0:
01111 = Generates interrupt after completion of every 16th sample/conversion operation
01110 = Generates interrupt after completion of every 15th sample/conversion operation
•
•
•
00001 = Generates interrupt after completion of every 2nd sample/conversion operation
00000 = Generates interrupt after completion of every sample/conversion operation
When ADDMAEN = 1:
11111 = Increments the DMA address after completion of every 32nd sample/conversion operation
11110 = Increments the DMA address after completion of every 31st sample/conversion operation
•
•
•
00001 = Increments the DMA address after completion of every 2nd sample/conversion operation
00000 = Increments the DMA address after completion of every sample/conversion operation

REGISTER 25-4: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **HLMS:** High or Low-Level Masking Select bits
1 = The masking (blanking) function will prevent any asserted (‘0’) comparator signal from propagating
0 = The masking (blanking) function will prevent any asserted (‘1’) comparator signal from propagating

bit 14 **Unimplemented:** Read as '0'

bit 13 **OCEN:** OR Gate C Input Enable bit
1 = MCI is connected to OR gate
0 = MCI is not connected to OR gate

bit 12 **OCNEN:** OR Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to OR gate
0 = Inverted MCI is not connected to OR gate

bit 11 **OBEN:** OR Gate B Input Enable bit
1 = MBI is connected to OR gate
0 = MBI is not connected to OR gate

bit 10 **OBNEN:** OR Gate B Input Inverted Enable bit
1 = Inverted MBI is connected to OR gate
0 = Inverted MBI is not connected to OR gate

bit 9 **OAEN:** OR Gate A Input Enable bit
1 = MAI is connected to OR gate
0 = MAI is not connected to OR gate

bit 8 **OANEN:** OR Gate A Input Inverted Enable bit
1 = Inverted MAI is connected to OR gate
0 = Inverted MAI is not connected to OR gate

bit 7 **NAGS:** AND Gate Output Inverted Enable bit
1 = Inverted ANDI is connected to OR gate
0 = Inverted ANDI is not connected to OR gate

bit 6 **PAGS:** AND Gate Output Enable bit
1 = ANDI is connected to OR gate
0 = ANDI is not connected to OR gate

bit 5 **ACEN:** AND Gate C Input Enable bit
1 = MCI is connected to AND gate
0 = MCI is not connected to AND gate

bit 4 **ACNEN:** AND Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to AND gate
0 = Inverted MCI is not connected to AND gate

REGISTER 28-1: PMCON: PARALLEL MASTER PORT CONTROL REGISTER (CONTINUED)

bit 3 **CS1P:** Chip Select 0 Polarity bit(1)
1 = Active-high (PMCS1/PMCS)(2)
0 = Active-low (PMCS1/PMCS)

bit 2 **BEP:** Byte Enable Polarity bit
1 = Byte enable active-high (PMBE)
0 = Byte enable active-low (PMBE)

bit 1 **WRSP:** Write Strobe Polarity bit
For Slave Modes and Master Mode 2 (PMMODE<9:8> = 00, 01, 10):
1 = Write strobe is active-high (PMWR)
0 = Write strobe is active-low (PMWR)
For Master Mode 1 (PMMODE<9:8> = 11):
1 = Enables strobe active-high (PMENB)
0 = Enables strobe active-low (PMENB)

bit 0 **RDSP:** Read Strobe Polarity bit
For Slave Modes and Master Mode 2 (PMMODE<9:8> = 00, 01, 10):
1 = Read strobe is active-high (PMRD)
0 = Read strobe is active-low (PMRD)
For Master Mode 1 (PMMODE<9:8> = 11):
1 = Enables strobe active-high (PMRD/PMWR)
0 = Enables strobe active-low (PMRD/PMWR)

Note 1: These bits have no effect when their corresponding pins are used as address lines.
2: PMCS1 applies to Master mode and PMCS applies to Slave mode.

REGISTER 28-2: PMMODE: PARALLEL MASTER PORT MODE REGISTER (CONTINUED)

bit 1-0 **WAITE<1:0>:** Data Hold After Strobe Wait State Configuration bits(1,2,3)

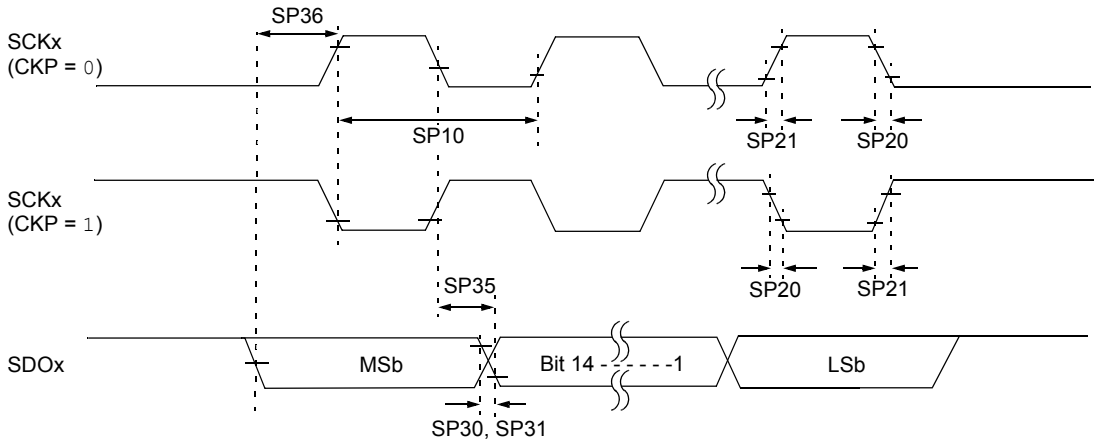
11 = Wait of 4 TP
10 = Wait of 3 TP
01 = Wait of 2 TP
00 = Wait of 1 TP

Note 1: The applied Wait state depends on whether data and address are multiplexed or demultiplexed. See **Section 28.4.1.8. "Wait States"** in **Section 28. "Parallel Master Port (PMP)"** (DS70576) in the *"dsPIC33E/PIC24E Family Reference Manual"* for more information.

2: WAITB<1:0> and WAITE<1:0> bits are ignored whenever WAITM<3:0> = 0000.

3: TP = 1/FP.

FIGURE 32-16: SPI1, SPI3 AND SPI4 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 32-1 for load conditions.

TABLE 32-34: SPI1, SPI3 AND SPI4 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	15	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 32-38: SPI1, SPI3 AND SPI4 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output, High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	50	ns	

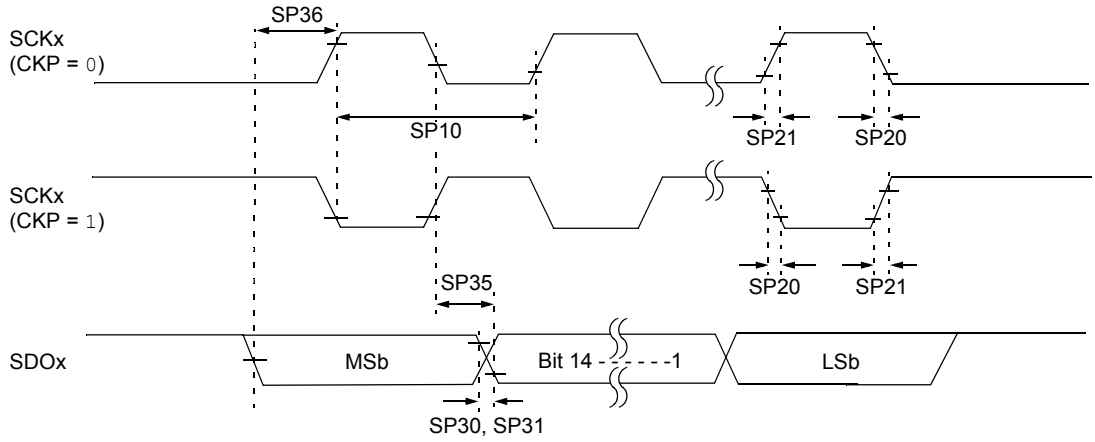
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCKx clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 32-24: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 32-1 for load conditions.

TABLE 32-42: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	15	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	

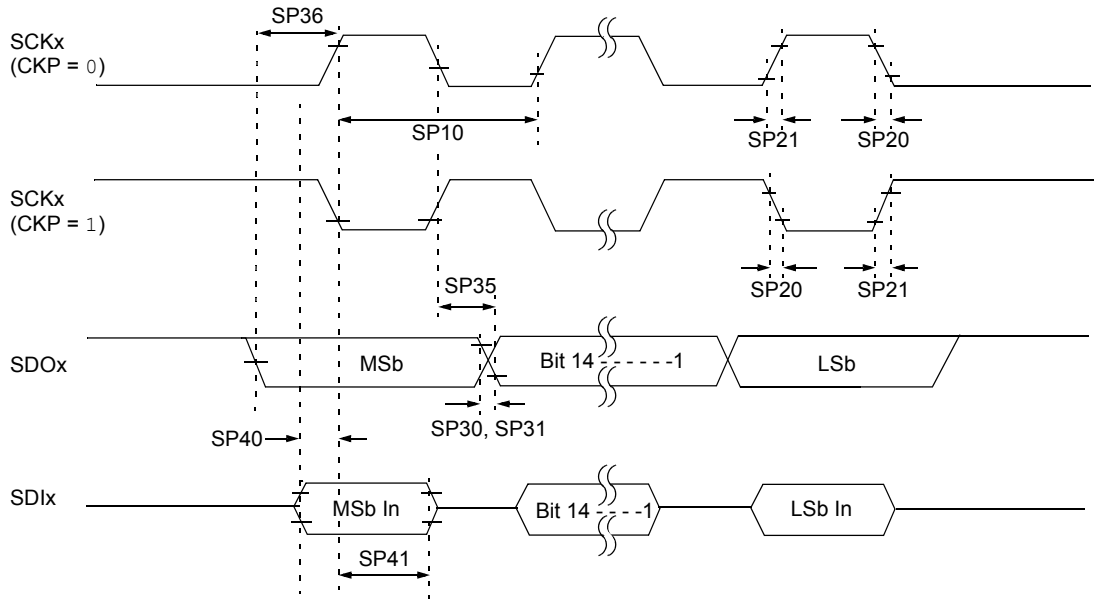
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 32-25: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 32-1 for load conditions.

TABLE 32-43: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	10	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

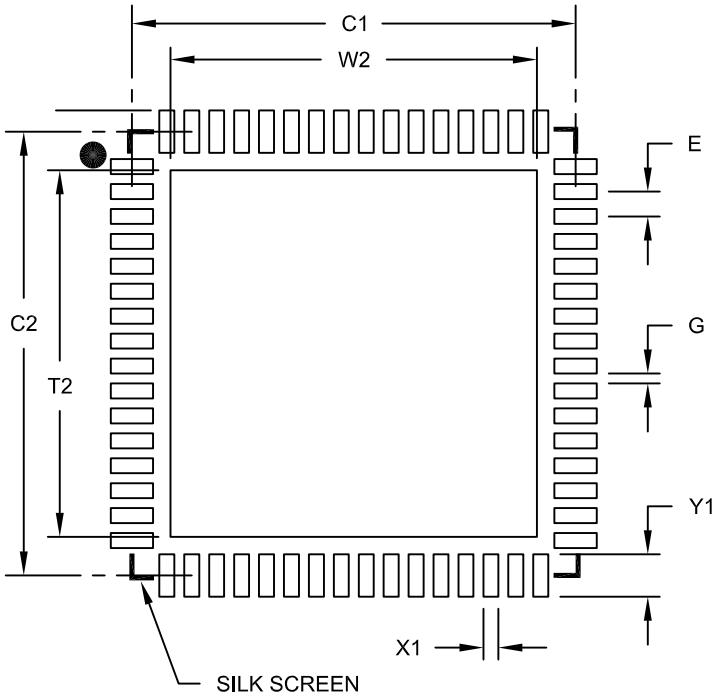
2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	W2			7.35
Optional Center Pad Length	T2			7.35
Contact Pad Spacing	C1		8.90	
Contact Pad Spacing	C2		8.90	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.85
Distance Between Pads	G	0.20		

Notes:

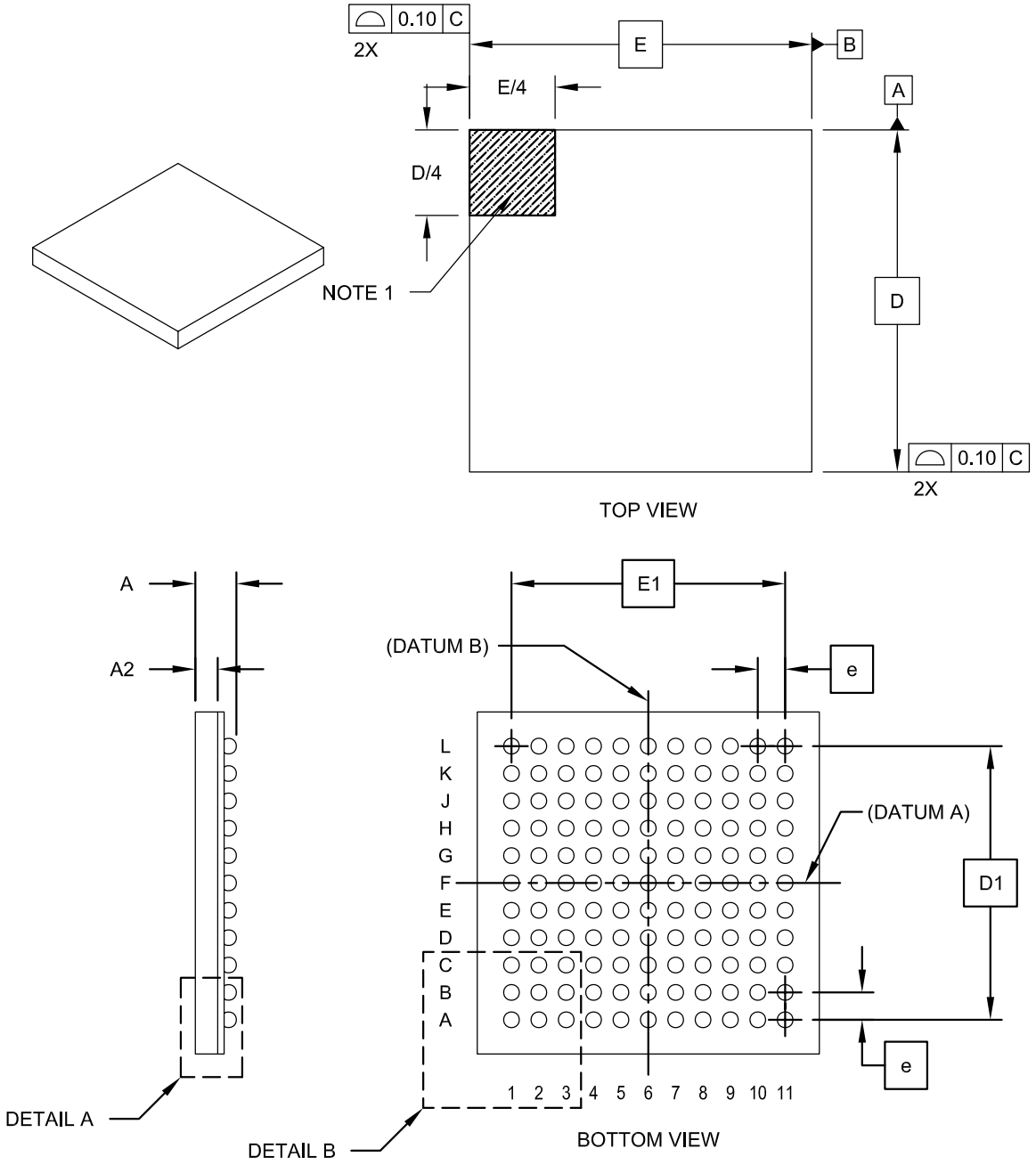
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2149A

121-Lead Plastic Thin Profile Ball Grid Array (BG) - 10x10x1.10 mm Body [TFBGA–Formerly XBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-148 Rev D Sheet 1 of 2